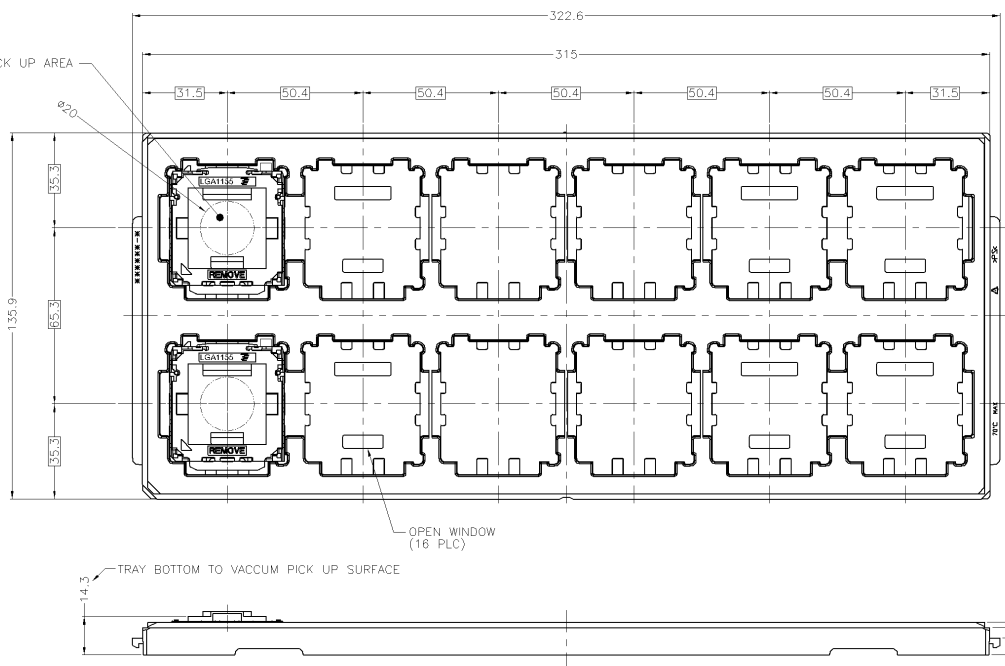


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REV. NO.		DATE		BY		APPROVED	
E1	REVISED	01JUL'11	J.M	T.N			



1. MATERIAL
- ① HOUSING : HIGH TEMP. THERMO-PLASTIC, UL94V-0, BLACK
 - ② CONTACT : COPPER ALLOY
FINISH : Au PL. AT CONTACT AREA ON OVERALL OVER Ni UNDER PL. 0.00127 MIN.
 - ③ SOLDER BALL : Sn/Ag/Cu
 - ④ CAP : HIGH TEMP. THERMO-PLASTIC, UL94V-0, BLACK
- △ INDICATED DATE CODE ON THE H5G

2069965-3	GOLD FLASH PL
2069965-2	0.76 um MIN Au PL
2069965-1	0.38 um MIN Au PL
PART NUMBER	DESCRIPTION

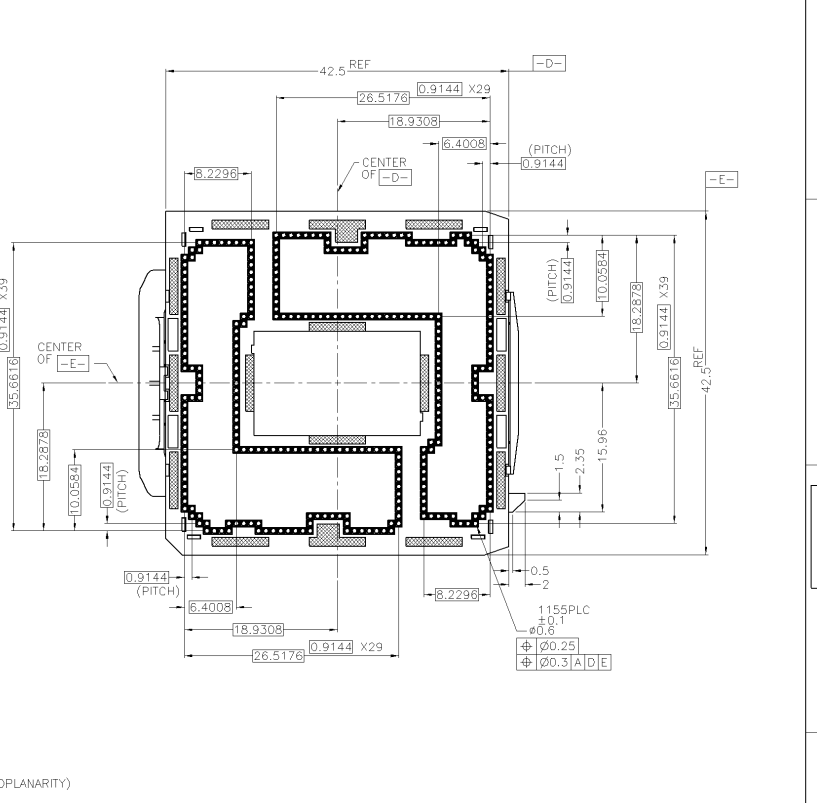
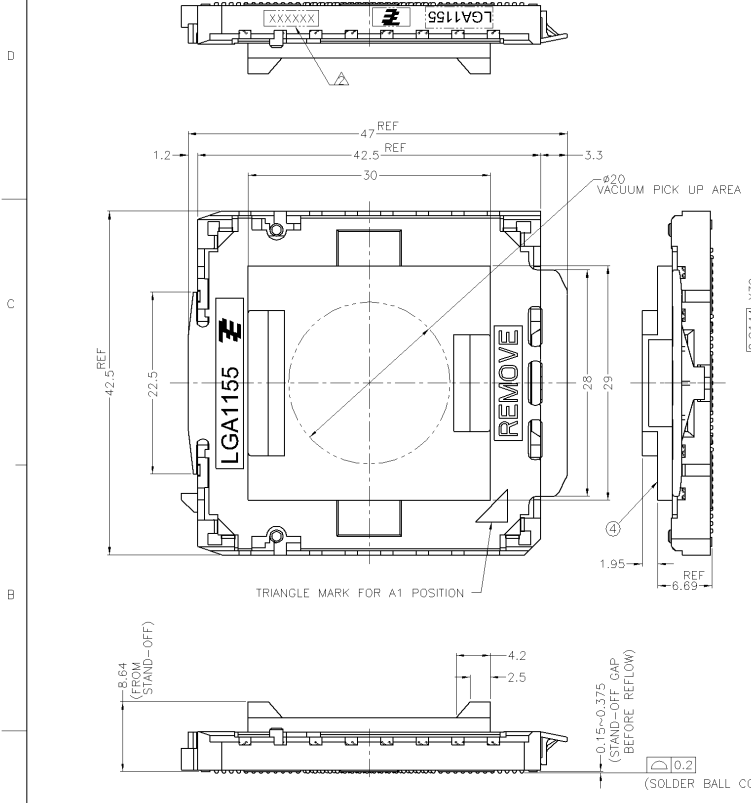
THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNER MIZUSHIMA	100AN2010	DATE	100AN2010
CHK H. TAGUCHI	100AN2010	SCALE	1/1
APP NAKASHIMA	100AN2010	PRODUCT SPEC	10S-78586
APPROVED NAKASHIMA	100AN2010	APPLICATION SPEC	10S-5444
MATERIAL	FINISH	WEIGHT	9.8g
CUSTOMER DRAWING		SIZE	A2
		CAGE CODE	00779
		DRAWING NO.	2069965
		RESTRICTED TO	-
		SCALE	1:1
		SHEET	1 of 5
		REV	E1

TE Connectivity
 SOCKET ASSY
 LGA1155

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REVISONS				DATE	OWN	APPD	
NO.	DESCRIPTION	DATE	OWN	APPD	DATE	OWN	APPD
-	SEE SHEET 1	-	-	-	-	-	-

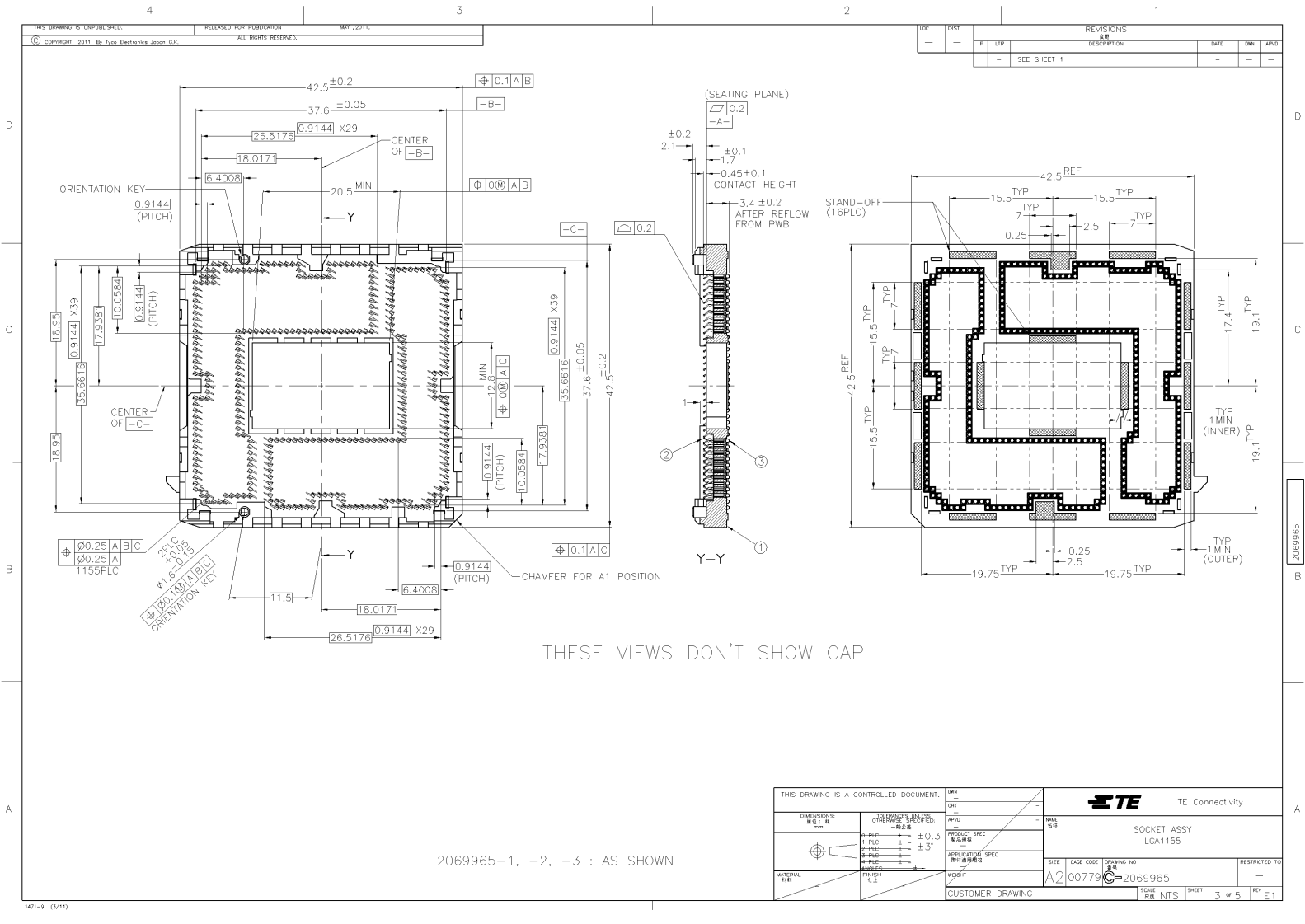


2069965-1, -2, -3 : AS SHOWN

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	OWN	TE Connectivity	
DRAWING NO.	DATE	DATE	OWN	NAME	SOCKET ASSY
					LGA1155
TOLERANCES UNLESS OTHERWISE SPECIFIED:	±0.3	PRODUCT SPEC		SIZE	A2
	±3°	APPLICATION SPEC		CAGE CODE	00779
				DRAWING NO.	2069965
MATERIAL		WEIGHT		RESTRICTED TO	
				CUSTOMER DRAWING	
				REAL NTS	SHEET 2 of 5
					REV E1

2069965

A



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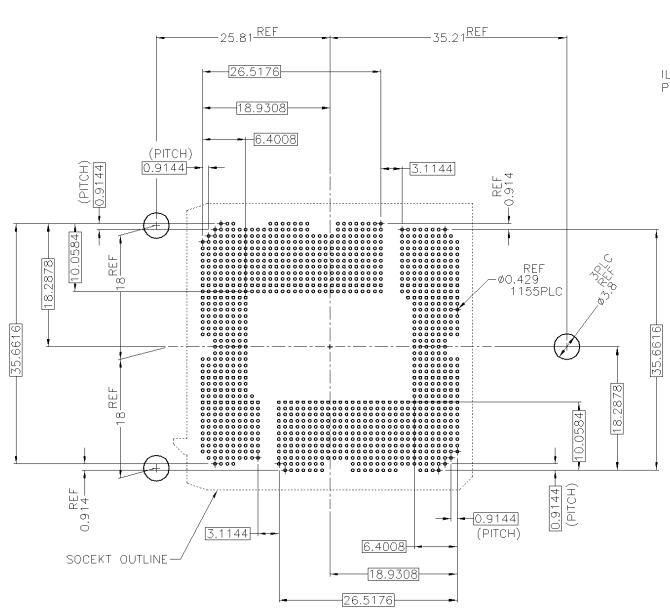
REVISIONS					
REV.	DATE	BY	CHKD.	APPD.	DESCRIPTION
-	-	-	-	-	SEE SHEET 1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	TE Connectivity	
DIMENSIONS 寸法	TOLERANCES UNLESS OTHERWISE SPECIFIED 公差	REV.	NAME 品名	
±0.1	±0.3	DATE	SOCKET ASSY	
±0.05	±0.1	REV.	LGA1155	
±0.02	±0.05	DATE	SIZE	DRAWING NO.
±0.01	±0.02	REV.	A2	00779
		DATE	CAGE CODE	2069965
MATERIAL	FINISH	DATE	WEIGHT	RESTRICTED TO
		REV.	CUSTOMER DRAWING	
		DATE	SCALE	NTS
		REV.	3	5
		DATE	REV.	E1

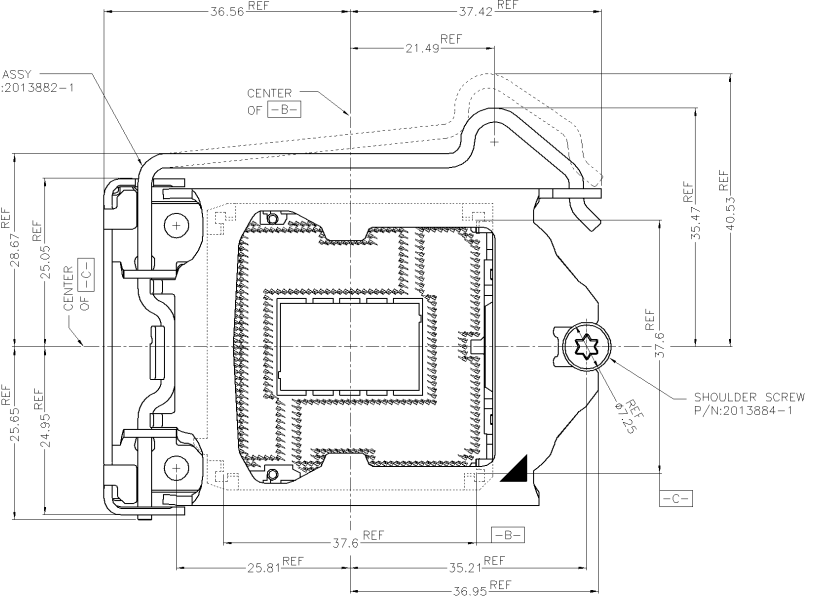
1471-8 (3/11)

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REV. NO.		DESCRIPTION		DATE	BY	APPV
1		SEE SHEET 1				



REFERENCE PATTERN LAYOUT

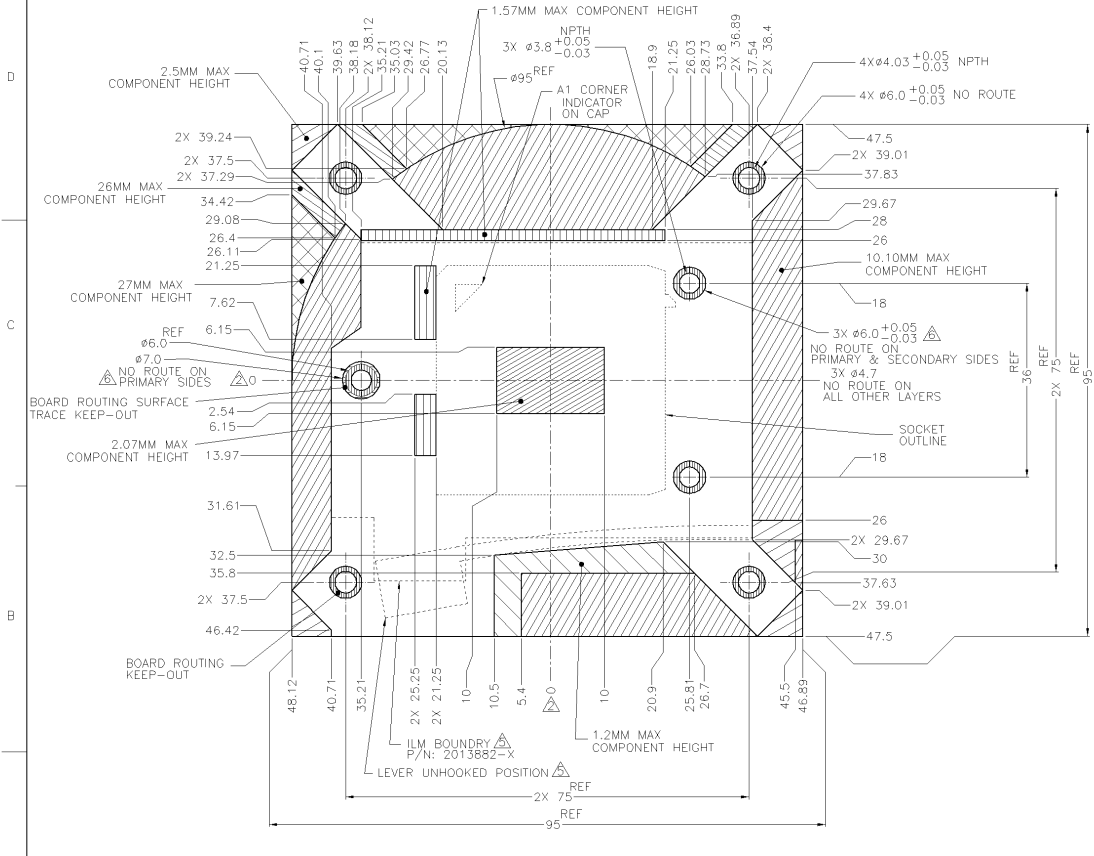


ILM ASSEMBLY OCCUPATION AREA (REFERENCE)
CAP IS NOT SHOWN ON THIS VIEW

FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	TE Connectivity	
DIMENSIONS	TOLERANCES UNLESS OTHERWISE SPECIFIED	REV	NAME	
mm	mm	01	SOCKET ASSY	
			LGA1155	
			SIZE	DATE CODE
			A2	00779
			CAGE CODE	DRAWING NO
			2069965	2069965
MATERIAL	FINISH	WEIGHT	RESTRICTED TO	
CUSTOMER DRAWING			SCALE	SHEET
			1:1	4 of 5

REV	DATE	DESCRIPTION	BY	CHK	APPD
1		SEE SHEET 1			



NOTES (APPLIED TO SHEET 5 OF 5):
 1. DIMENSIONS ARE IN MILLIMETERS
 2. GEOMETRIC CENTER OF SOCKET HOUSING CAVITY
 3. BOARD COMPONENT KEEP-INS AND MECHANICAL ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES, ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 4. ASSUME SYMMETRY FOR UNDEFINED CORNERS AND EDGES.
 5. FOR UNDEFINED DIMENSIONS, REFER TO THERMAL AND MECHANICAL DESIGN GUIDELINE PROVIDED BY INTEL CORPORATION.
 6. COPPER PAD ON PRIMARY SIDE, NON-GROUNDED.
 7. COPPER PAD CAN INSET A MAXIMUM OF 0.127MM FROM THE NO ROUTE EDGE
 8. COMBINED COMPONENT AND SOLDER PASTE HEIGHT INCLUDING TOLERANCES AFTER REFLOW.

LEGEND	
	SOCKET/THERMAL/MECHANICAL COMPONENT KEEP-INS
	10.10MM MAX COMPONENT HEIGHT
	1.57MM MAX COMPONENT HEIGHT
	1.2MM MAX COMPONENT HEIGHT
	BOARD ROUTING KEEP-OUT
	27MM MAX COMPONENT HEIGHT
	BOARD ROUTING SURFACE TRACE KEEP-OUT
	2.07MM MAX COMPONENT HEIGHT
	2.5MM MAX COMPONENT HEIGHT
	26MM MAX COMPONENT HEIGHT

COMPONENT KEEP-INS AND MECHANICAL COMPONENT KEEP-OUTS FOR REFERENCE ONLY. PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

THIS DRAWING IS A CONTROLLED DOCUMENT.

<p>DIMENSIONS: 尺寸</p> <p>TO TOLERANCE SELECTED: 公差选择</p> <p>OTHER TOLERANCE SPECIFIED: 其他公差</p> <p>APPROX: ±0.3</p> <p>PRECISION SPEC: ±0.05</p> <p>APPLICATION SPEC: ±0.3</p>	<p>DATE: 日期</p> <p>NAME: 姓名</p> <p>SIZE: 尺寸</p> <p>CAGE CODE: 笼号</p> <p>DRAWING NO: 图号</p> <p>00779</p> <p>2069965</p> <p>RESTRICTED TO: 限制</p> <p>—</p>	<p>TE Connectivity</p> <p>SOCKET ASSY</p> <p>LGA1155</p> <p>REAL NTS</p> <p>SHEET 5 of 5</p> <p>REV E1</p>
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CUSTOMER DRAWING